

## Results

We are pleased to report that ASM Pacific Technology Limited and its subsidiaries (the "Group" or "ASM") achieved turnover amounting to HK\$3,828,930,000 in the fiscal year ended 31 December 2004, representing an increase of 47.0% as compared with HK\$2,604,823,000 for the previous year. The Group's consolidated net profit after tax for the year is HK\$1,002,595,000, which is 87.1% higher than the previous year's net profit of HK\$535,873,000. Basic earnings per share for the year amounted to HK\$2.61 (2003: HK\$1.40).

## Dividend

An interim dividend of HK\$0.45 (2003: HK\$0.36) and a special dividend of HK\$0.55 per share were paid in August 2004. Having established a solid foundation in the microelectronics market over the years, ASM intends to further its organic growth path in the near term through enlarging its market share with diversified, high performance products. There is no short term need for major cash outlay and the Group has consistently generated significant positive cash flow from operations in each of the past five years. In view of our strong liquidity and rising equity base, the Board of Directors has decided to recommend a final dividend of HK\$1.05 (2003: HK\$0.84) per share payable on or around 29 April 2005, making a total dividend payment of HK\$2.05 (2003: HK\$1.20) per share for the year ended 31 December 2004, inclusive of HK\$0.55 per share of special dividend. This translates into a 78.6% dividend payout ratio for the current year profit; representing a prudent decision to return current excessive cash holdings to our shareholders while continuing to operate the Group with the optimum shareholders' funds.

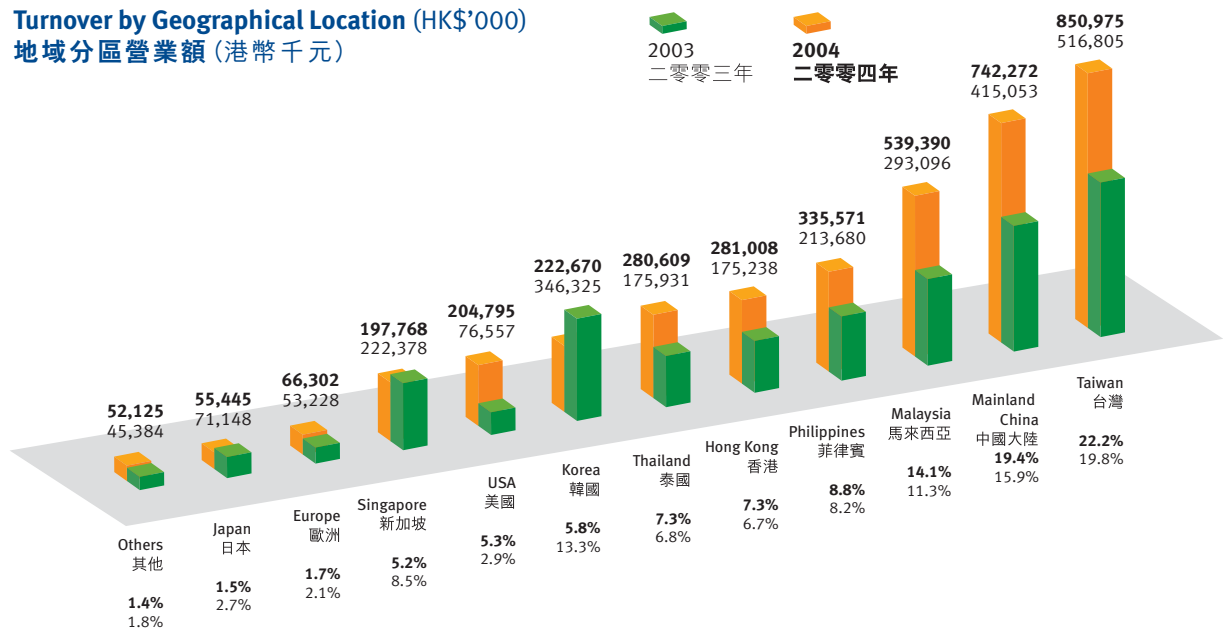
## 業績

謹此欣然報告，ASM Pacific Technology Limited 及其附屬公司（「集團」或「ASM」）於截至二零零四年十二月三十一日止年度錄得營業額為港幣 3,828,930,000 元，與上年度港幣 2,604,823,000 元比較，增加百分之四十七。本年度集團的綜合除稅後淨溢利為港幣 1,002,595,000 元，較上年度淨溢利港幣 535,873,000 元增加百分之八十七點一。是年度每股基本溢利為港幣 2.61 元（二零零三年：港幣 1.40 元）。

## 派息

中期股息每股港幣 0.45 元（二零零三年：港幣 0.36 元）及特別股息每股港幣 0.55 元已於二零零四年八月派發。憑藉過去數年在微電子市場所建立的穩固基礎，集團未來將致力透過多元化及高性能的產品擴大市場佔有率，積極加快本體增長。集團在短期內沒有重大現金開支，並於過去五年持續從營運產生正現金流量。在擁有充裕的流動資金和股本增加的情況下，董事會現建議派發末期股息每股港幣 1.05 元（二零零三年：港幣 0.84 元），並於二零零五年四月二十九日左右派發。連同每股港幣 0.55 元之特別股息，集團截至二零零四年十二月三十一日止年度全年合計每股派息為港幣 2.05 元（二零零三年：港幣 1.20 元）。本年度派息率為百分之七十八點六，充份顯示集團決定將過剩現金回饋股東時已作審慎考慮，並預留適量的股東資金作集團營運之用。

## Turnover by Geographical Location (HK\$'000) 地域分區營業額 (港幣千元)

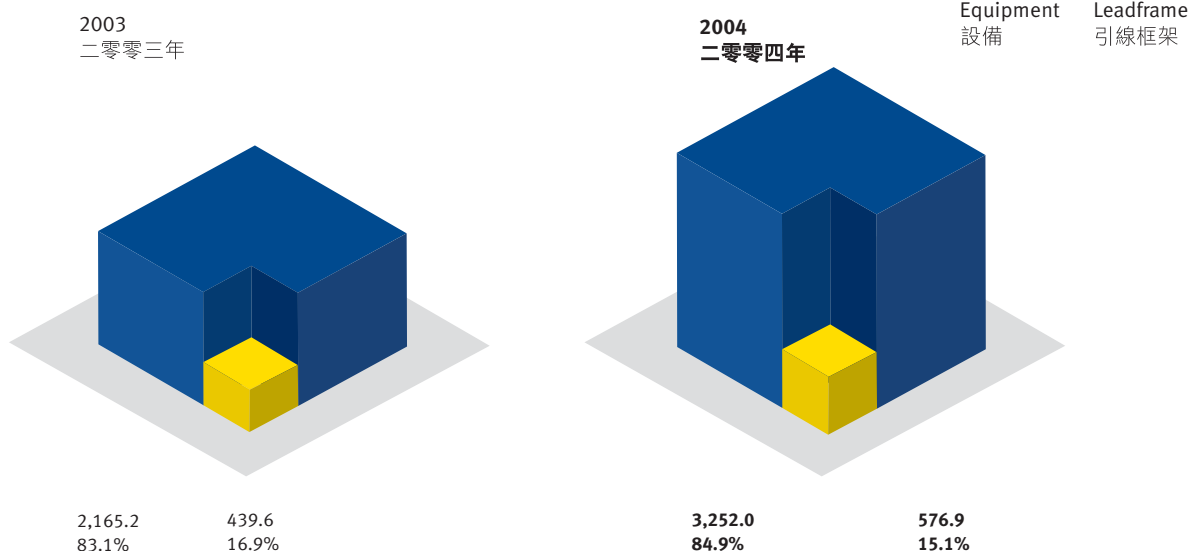


Review

Although gaining wide-spread acceptance in recent years, information technology (IT) planning tools and out-sourcing strategy have really made their presence felt over the last twelve months. Every sector of the electronics food chain monitored their projected demands and inventory levels, making prudent decisions to quickly revise their production schedules upward or downward as needed. The four quarters of 2004 were as different as the four seasons of the year. Buoyed by optimistic projections of electronic end-product demands at the beginning of the year, the semiconductor industry promptly reacted and aggressively installed capacity for the latest BGA and chip scale package (CSP), generating strong requirements for die and wire bonders used in stacked die and fine pitch bonding. For most companies, the decent beginning of the year order backlogs were followed by higher outputs in the second quarter. Unfortunately, when electronics companies adjusted their outputs to optimize their inventory levels, the inflection point for assembly equipment demands clearly occurred in the middle of the third quarter, with the equipment market turning from across-the-board boom to selected purchases addressing specific capability and package requirements. During the fourth quarter, every company was anxiously looking forward for spring to come.

Compared with previous years, 2004 overall was a year of continued recovery and excellent growth for both the semiconductor and its equipment industries, both in terms of unit volume and dollar sales. With the healthy world economic conditions and increasing popularity of hand-held electronic goods, the semiconductor industry expanded by 24 – 29% in revenue while the assembly and packaging equipment market increased by 44 – 49% in 2004, according to the year-end estimates by various industry analysts. Disregarding the incorrect mid-year adjustments by various analysts that reflected the prevailing optimism at the time, both the semiconductor and assembly equipment industries performed basically in line with previous projections at the beginning of the year.

Turnover by Products (HK\$Million)  
產品分類營業額 (港幣百萬元)



業務回顧

資訊科技規劃軟件及企業外判模式雖然於近年已廣被接納，然而真正被獲得廣泛採用實為過去十二個月始出現之情況。整個電子生產鏈內每個領域之企業均密切監察其預估需求及存貨水平，按需要審慎決定並迅速調整其生產計劃，因此二零零四年的四個季度便如四季般呈現不同的市場狀況。鑑於年初業內對電子產品需求的樂觀預測，半導體行業積極投入提升最新型BGA及晶體度包裝的產能，因而對應用在大量管芯及微距焊線上之管芯焊機及焊線機的需求大增。於年初大部份企業未完成之訂單高企，故第二季度之產量亦較高。但不幸地，當電子企業降低其產量以完善化存貨水平時，裝嵌設備行業的需求亦於第三季度中期受到影響，設備市場由全面性的迅速增長轉為對特定性能及包裝要求的選擇性採購。於第四季度，所有企業均急切地期待著春季的來臨。

相較過去數年，二零零四年整體而言是半導體及其設備行業持續復甦、產量及銷售額均強勁增長的一年。在利好的全球經濟環境及手提電子產品日益普及的情況下，綜合各行業分析員的年終預測，二零零四年半導體行業的收入增長為百分之二十四至二十九，裝嵌及包裝設備市場則增長百分之四十四至四十九。撇除年中部份分析員按當時樂觀市況所作出的不正確預測調整，半導體行業及裝嵌設備行業的表現基本上均合乎年初的市場預測。

### Review continued

Consistent with our results over the last five years, ASM once again outperformed its industry peers and gained market share, maintaining its number one position in the assembly and packaging equipment industry. We achieved a Group turnover of US\$491.6 million and net profit of HK\$1,002.6 million, a growth of 47.0% (2003: 41.1%) and 87.1% (2003: 88.2%) respectively, with both Group turnover and net profit representing the second highest numbers in ASM's corporate history. In fact, capitalizing on the strong market environment during the first half of 2004, the Group achieved new heights in revenues and profitability over the six-month period, surpassing previous peaks in year 2000. For the whole year, return on capital employed and on sales was 48.8% and 27.5% respectively; both are ASM's second highest on record. With outputs catching up on demands starting the second quarter and weaker inflows of orders during the second half year, book-to-bill ratio was 0.89 for the year and our ending order backlog as of 31 December 2004 was US\$63 million (US\$119 million as of 31 December 2003).

In 2004, sales attributable to our five largest customers combined were 28.0% of the total, with only one customer exceeding 10%, clear evidence of the success of our continuing diversified market strategy. We also enjoyed a good geographical spread mirroring the investment climate of the industry, with Taiwan being our largest (22.2%) market and followed by China (19.4%). For the latter, shipments (US\$95.3 million) were substantially (78.8%) higher than the preceding year, creating another new record for the territory.

A comparison of the revenue peaks and valleys of our leading competitors in 2004 clearly illustrates the importance of offering diversified products to serve broad application markets in a rapidly changing economic environment. ASM has structured its business strategy on such a foundation, resulting in our financial performance repeatedly outshining our competitors at challenging times. Our equipment business, which represented 84.9% of the Group's turnover in 2004, grew 50.2% to US\$417.5 million, achieving a higher growth rate than our major competitors. We further enlarged the 2004 revenue gap between ourselves and our closest rival to US\$108 million or 34.9%, larger than the 18.5% and 4.7% gaps of the two preceding calendar years. Such a strong financial performance clearly reflects ASM's leadership position in the two largest market segments – the wire and die bonder areas – and the growing acceptance of other ASM products and services.

### 業務回顧 續

貫徹集團於過去五年的卓越表現，ASM再度超越同儕並提升市場佔有率，繼續佔據裝嵌及包裝設備業內第一位。集團錄得營業額四億九千一百六十萬美元及純利十億零二百六十萬港元，增長幅度分別達百分之四十七（二零零三年：百分之四十一點一）及百分之八十七點一（二零零三年：百分之八十八點二），是ASM有史以來的第二高。事實上，受惠於二零零四年上半年利好的市場環境，集團於此半年期內的營業額及純利均創歷史新高，超越二零零零年所創之紀錄。集團是年度的資本回報率及銷售利潤率分別為百分之四十八點八及百分之二十七點五，兩者同是集團有史以來的第二高。由於第二季度開始產量逐漸追上需求及下半年度新增訂單數目較少，本年度的訂貨對付運比率為零點八九，於二零零四年十二月三十一日的未完成訂單總值為六千三百萬美元（於二零零三年十二月三十一日為一億一千九百萬美元）。

於二零零四年，我們的五大客戶共佔集團營業額百分之二十八，其中只有一個客戶的銷售額佔超過百分之十，足以證明集團堅持市場多元化之策略是成功的。此外，集團的業務廣泛分佈各地，足以反映業內的投資氣候。當中台灣是集團最主要的市場，佔營業額百分之二十二點二，中國市場緊隨其後佔百分之十九點四。集團於中國市場的付運量（九千五百三十萬美元）較上年度大幅上升百分之七十八點八，再次創新紀錄。

集團以於二零零四年最高及最低的收益水平與主要競爭對手相比較，清楚反映在瞬息萬變的經濟環境下，提供多元化產品及服務以應付不同應用市場是十分重要的。ASM在此基礎上所制定的業務策略正是集團在艱巨市況下仍能超越對手成功要點。二零零四年設備業務佔集團營業額百分之八十四點九，較去年增長百分之五十點二達至四億一千七百五十萬美元，增長幅度超越業內主要競爭對手。此外，於二零零四年我們進一步拉闊與最接近的競爭對手之收益差距至一億零八百萬美元或百分之三十四點九，高於過去兩年的百分之十八點五及百分之四點七。集團獲此佳績，充份反映集團於兩大主要市場 – 焊線機及管芯焊機 – 的領導地位，及客戶對ASM其他產品及服務的接受程度也日益提升。

### Review continued

Heavy market demands coupled with capacity expansion and operational improvements in both our new China factory and Singapore plants resulted in 31.2% growth of our leadframe business to US\$74.1 million in 2004, representing 15.1% of the Group's turnover. Both our stamped and QFN etched frames made good inroads in our target markets, growing faster than the leadframe industry as a whole which increased by 14.3% last year according to SEMI's January 2005 report. The strategic realignment of our leadframe operation continued as planned, with our 280,000 sq.ft. factory in Pasir Gudang, Johor Bahru, Malaysia ready for occupation by end of 2004. We have been relocating our machine part production and post-plating activities to this new Malaysian plant since the beginning of the year, to be followed by the plating operation during the first half of 2005. Upon the successful transfer of all plating activities from our Singapore plant to this new Malaysian factory, we intend to add stamping production to the new facility to effectively address the stamped frame business in Malaysia and Singapore markets.

Tech companies increasingly have to deliver solutions that respond to the end users' demands. Our customers' unrelenting needs for ever lower assembly and packaging costs, new package types like QFN, stacked die and flip chip, and the ceaseless push of the technology envelope on fine pitch wire bonding, thin die attachment and ultra thin molded packages call for innovative solutions and strong R&D commitments from equipment suppliers.

Last year we launched our Twin Eagle wire bonder (35 microns capability) featuring two bonding heads, delivering a productivity gain of 80 – 100% depending on applications. It requires only 30% more floor space than a single head wire bonder, making our Twin Eagle the highest throughput and the lowest cost-of-ownership bonding machine in the world today. Concurrently, another new model wire bonder, the Eagle 60 AP, capable of 30 microns linear pad pitch bonding and 10% faster than our Eagle 60, also migrated to volume production towards end of the year. In addition, we provide a process solution to pick ultra thin (down to 50 microns) die with our IC die bonder. We also offer a new IC die bonder catering for smaller die sizes with a 30% productivity enhancement over our universal platform. Besides our flip chip bonder for eutectic solder process, ASM also offers a complete solution for the small input/output (I/O) flip chip devices with gold or copper stud bumping and thermosonic attachment process. All these new products and solutions could not have been developed in such a short time without our 600 R&D staff located in Hong Kong and Singapore, and an ever-increasing R&D expenditure that amounted to HK\$262.6 million (2003: HK\$218.4 million), representing 8.1% of our current year's equipment sales.

### 業務回顧 續

受惠於龐大的市場需求、集團的產能擴充與中國及新加坡廠房的營運能力提升，引線框架業務於二零零四年度之營業額增加百分之三十一點二至七千四百一十萬美元，佔集團營業額百分之十五點一。集團的沖壓框架及QFN蝕片框架均成功打入目標市場，並較整體引線框架行業增長迅速。據SEMI二零零五年一月發表的報告顯示，引線框架市場去年整體的增長率為百分之十四點三。集團引線框架營運的策略性調整按計劃順利推行，其於馬來西亞Pasir Gudang, Johor Bahru佔地達280,000平方呎的新廠房亦如期於二零零四年底正式落成。集團已於二零零五年初開始將機件生產部份及電鍍後工序遷往馬來西亞廠房，而電鍍工序亦將於二零零五年上半年內搬遷至上址。隨著集團成功將新加坡廠房的所有電鍍工序遷往此馬來西亞新廠房，我們計劃進一步在這新廠房增設沖壓生產設備，令集團能更具效益地應付馬來西亞及新加坡之沖壓框架市場。

愈來愈多科技企業需因應最終客戶的需要提供適當方案。客戶對裝嵌及包裝成本持續下降、新的包裝模式如QFN、大量管芯及覆晶、與及微距焊線、微細管芯焊接及超微細鑄模包裝的技術突破等要求，促使設備供應商須提供創新解決方案及作出大量的研發投入。

去年，我們推出配備雙焊接器的Twin Eagle焊線機(具備35微米焊線能力)。此焊線機的生產力可因應不同的應用模式提升百分之八十至一百，而其所佔面積較目前之單焊接器焊線機僅增加百分之三十，令Twin Eagle成為現時世界上生產量最高及最具成本效益的焊線機。另一新型號的焊線機Eagle 60 AP，備有30微米直線墊距焊接能力，其速度較Eagle 60快百分之十，亦已於年底進入量產階段。此外，集團的集成電路管芯焊機為客戶提供技術方案以處理超微細(低至50微米)的管芯。我們亦推出新型號集成電路管芯焊機，適用於微型管芯，其焊接能力較現有產品快百分之三十。除共熔焊接技術的覆晶焊機以外，ASM亦為小型輸入/輸出(I/O)覆晶設備提供配備金或銅釘頭沖壓、易熔焊料及熱能超聲波覆晶技術的全面解決方案。集團能於短時間內成功研發此等產品及方案，全賴香港及新加坡共六百名研發人員的努力，及不斷增加投入的研發開支所致。本年度，集團的研發開支為二億六千二百六十萬港元(二零零三年：二億一千八百四十萬港元)，佔設備銷售額的百分之八點一。